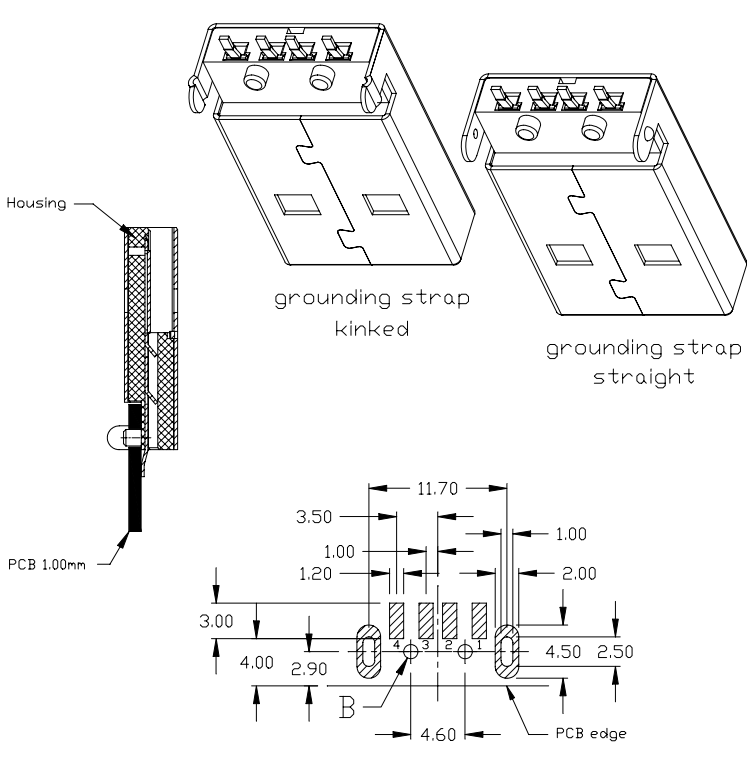
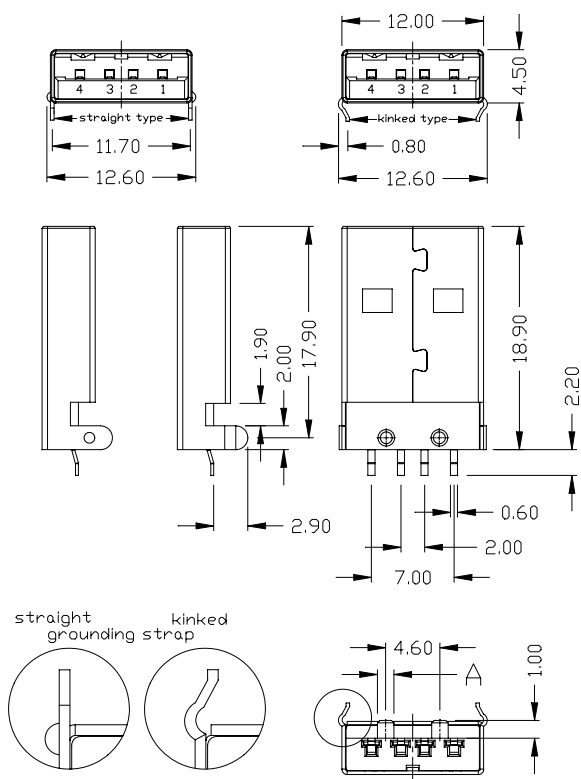


**SMT Type**



Recommendation:  
DIM. "B" =  $\varnothing$  1,20mm if locating peg  $\varnothing$  "A"=1,00mm  
DIM. "B" =  $\varnothing$  1,60mm if locating peg  $\varnothing$  "A"=1,40mm

**ORDER CODE**

**USP - B 04 - SA x 1 - XX**

**Housing Colour**

Black (Standard) = **B**  
others on request

**USB Corresponding**

**95** = Standard USB  
**98** = USB 2.0 corresponding

**Execution**

- 0** = kinked grounding pins; locating pegs  $\varnothing$ 1.00mm
- 1** = straight grounding pins; locating pegs  $\varnothing$ 1.00mm
- 2** = kinked grounding pins; locating pegs  $\varnothing$ 1.40mm
- 3** = straight grounding pins; locating pegs  $\varnothing$ 1.40mm  
(for locating peg dim. pls. go to drawing DIM. "A")

**Specification**

**Material**

Contact (RoHS compliant)	Brass
Plating:	
Contact area	Au flash over Ni (Std. USB) Au 30 $\mu$ " over Ni (USB 2.0 corresponding)
Solder area	Sn (leadfree)
Housing (RoHS compliant)	Nylon UL 94-V0
Shell (RoHS compliant)	brass, 80 $\mu$ "-120 $\mu$ " Ni plated

**Mechanical**

Mating cycles	1.500 min.
SMT coplanarity	0.10mm

**Electrical**

Current rating	1 A max. 1 Contact (Signal only)
Voltage rating	30V AC (rms)
Withstanding voltage	750V AC (rms) 1 Minute (Std. USB) 500V AC (rms) 1 Minute (USB 2.0)
Insulation resistance	1.000M $\Omega$ min. (500V DC)
Contact resistance	30m $\Omega$ max.

**Others**

Operating temperature	-30° C to +75° C
Processing temperature	+260° C +0/-5° C for 20~40sec.